

RoHS Compliant Product
A suffix of "-C" specifies halogen-free

FEATURES

- Heatsink Structure
- Low Profile, Typical Thickness 0.8mm
- Moisture Sensitivity: Level 1, Per J-STD-020
- High Temperature Soldering Guaranteed: 260°C/10 Seconds

MARKING

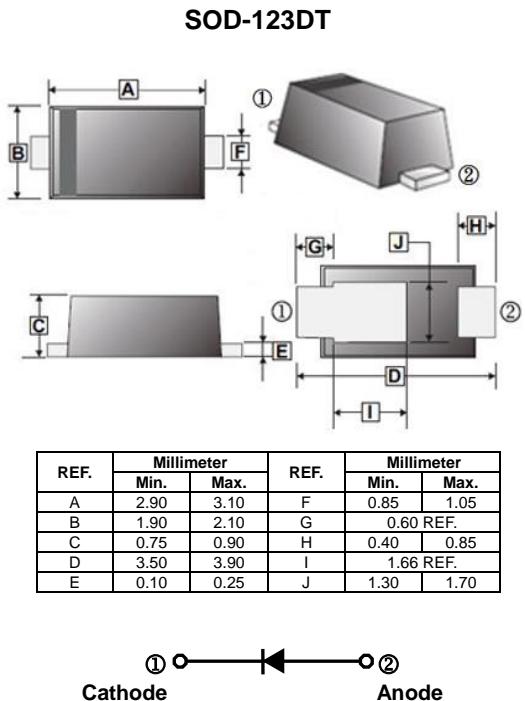
Part Number	SM220DT-C	SM230DT-C	SM240DT-C
Marking	PS22	PS23	PS24

PACKAGE INFORMATION

Package	MPQ	Leader Size
SOD-123DT	3K	7 inch

ORDER INFORMATION

Part Number	Type
SM220DT-C~SM240DT-C	Lead (Pb)-free and Halogen-free



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS (T_A=25°C unless otherwise specified)

Parameter	Symbol	Part Number			Unit	
		SM220DT-C	SM230DT-C	SM240DT-C		
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	20	30	40	V	
Maximum RMS Voltage	V _{RMS}	14	21	28	V	
Maximum DC Blocking Voltage	V _{DC}	20	30	40	V	
Maximum Average Forward Rectified Current	I _F	2			A	
Peak Forward Surge Current, 8.3ms Single Half Sine-Wave Superimposed on Rate Load	I _{FSM}	50			A	
Rating for Fusing (t<8.3ms)	I ² t	10			A ² S	
Maximum Instantaneous Forward Voltage @I _F =2A	T _A =25°C	V _F	0.51			
	T _A =125°C		0.45			
Maximum DC Reverse Current @ Rated DC Blocking Voltage	T _A =25°C	I _R	50			
	T _A =125°C		10			
Typical Junction Capacitance ³	C _J	115			pF	
Typical Thermal Resistance from Junction-Ambient ¹	R _{θJA}	60			°C/W	
Typical Thermal Resistance from Junction-Case ²	R _{θJC}	28				
Typical Thermal Resistance from Junction-Lead ¹	R _{θJL}	6				
Operating Junction & Storage Temperature	T _J , T _{STG}	-55~150			°C	

Notes:

1. The thermal resistance from junction to ambient or lead, mounted on P.C.B with 5x5mm copper pads, 2oz, FR-4 PCB.
2. The thermal resistance from junction to case, mounted on P.C.B with recommended copper pads, 2oz, FR-4 PCB.
3. Measured at 1MHz and applied reverse voltage of 4V D.C.

CHARACTERISTIC CURVES

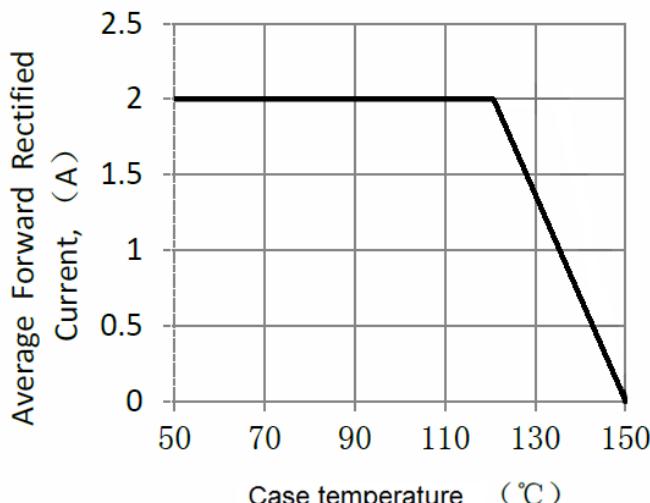


Figure 1. Forward Current Derating Curve

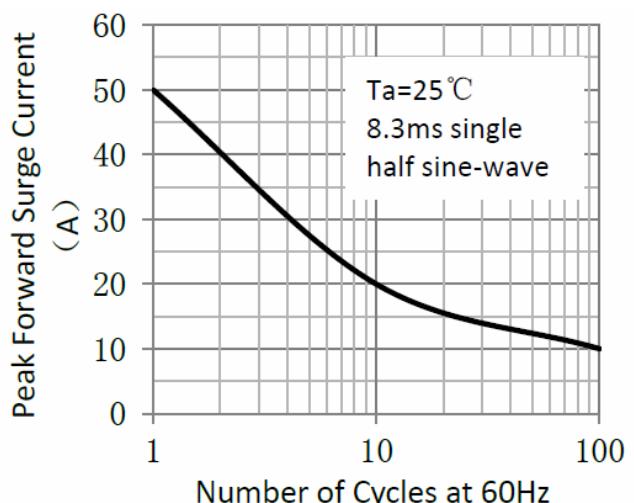


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

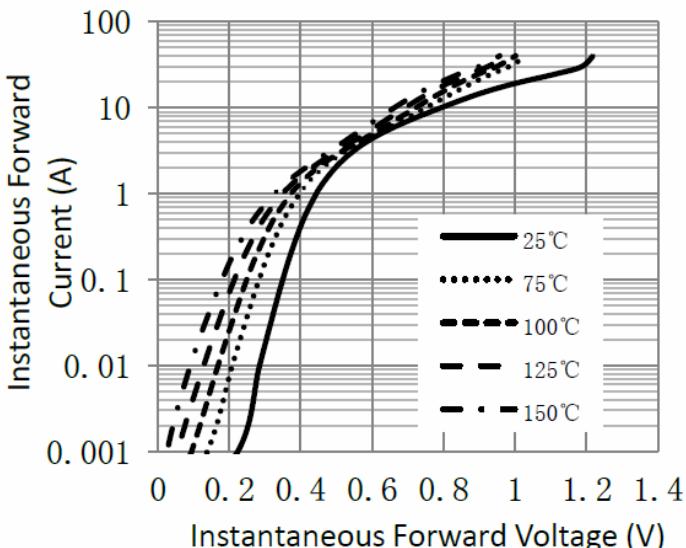


Figure 3. Typical Instantaneous Forward Characteristics

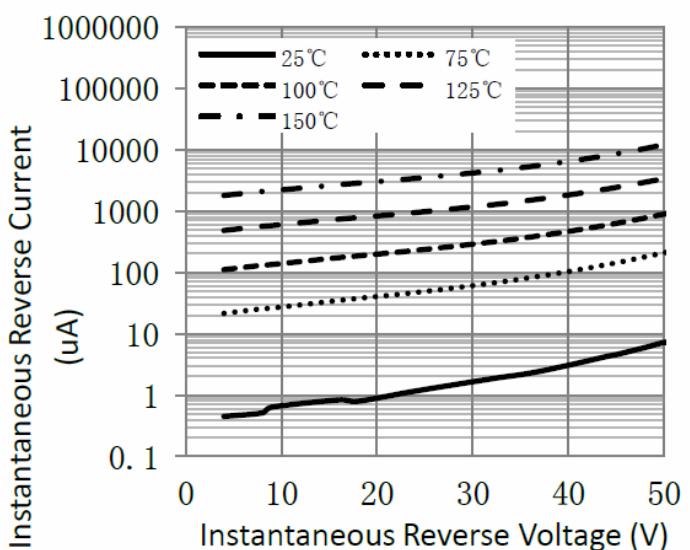


Figure 4. Typical Reverse Characteristics

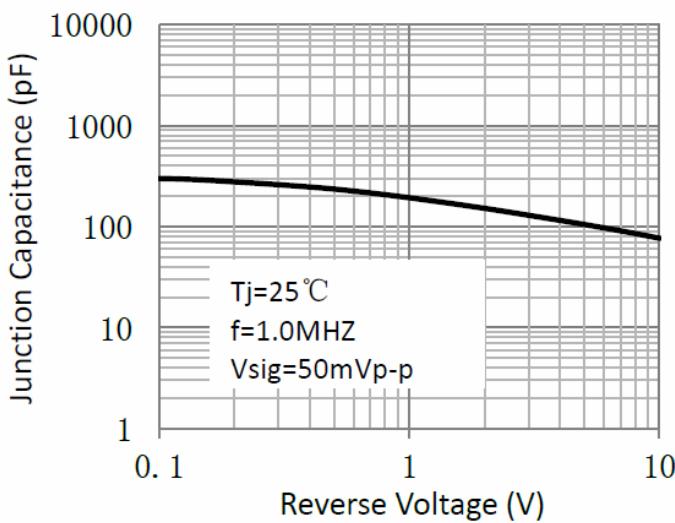


Figure 5. Typical Junction Capacitance

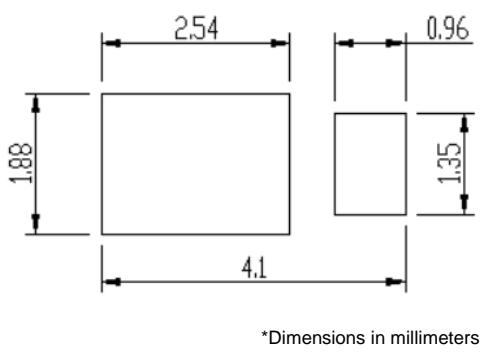


Figure 6. Mounting Pad Layout